

Title (en)

STRIP CONDUCTOR ARRANGEMENT AND METHOD FOR PRODUCING A STRIP CONDUCTOR ARRANGEMENT

Title (de)

LEITERBAHNANORDNUNG UND VERFAHREN ZUM HERSTELLEN EINER LEITERBAHNANORDNUNG

Title (fr)

ENSEMABLE PISTES CONDUCTRICES ET PROCEDE DE FABRICATION DUDIT ENSEMBLE

Publication

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Application

**EP 02754521 A 20020809**

Priority

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- DE 10140754 A 20010820

Abstract (en)

[origin: WO03019649A2] The invention relates to a conductor arrangement (100) containing a substrate (101) made from a first insulating material with a substrate surface (102), wherein at least two conductors (103) are arranged next to each other in the substrate (101). Said arrangement also comprises a buffer layer (104) made from a second insulating material arranged on the substrate (101) and a buffer layer surface (105) which is parallel to the substrate surface (102), at least one cavity (107) arranged between the conductors (103) preferably protruding deeper into the substrate (101) deeper than the conductors (103) in the substrate in relation to the buffer surface layer (105) and a covering layer made from a third insulating material (111) arranged on the buffer layer (104) and which completely closes the cavity (107) in relation to the buffer layer surface (105).

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Citation (search report)

See references of WO 03019649A2

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US 6242336 B1 20010605 - UEDA TETSUYA [JP], et al

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